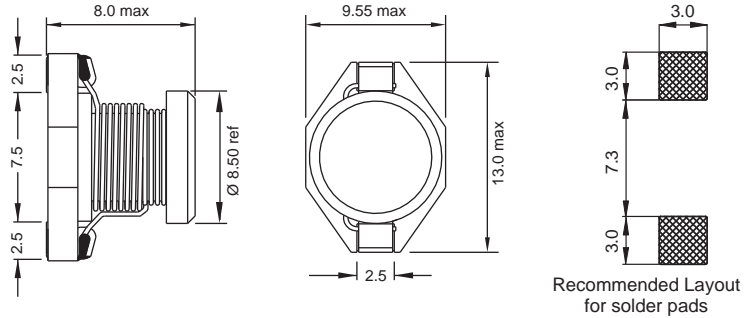
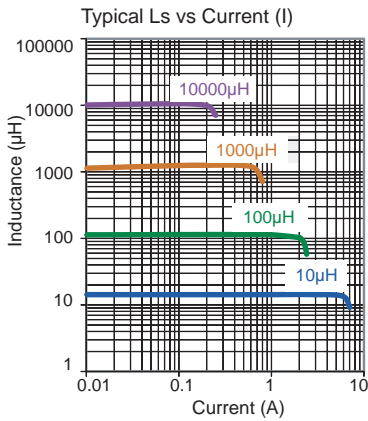
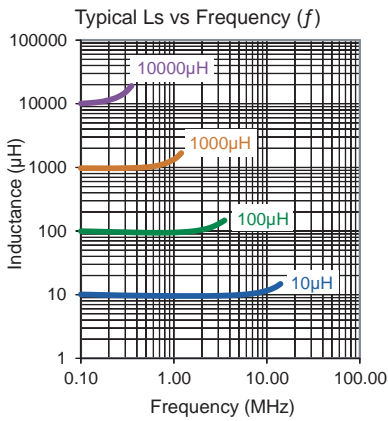


# PISP



Recommended Layout for solder pads



Part No	Inductance L ( $\mu\text{H}$ )	$f_L$ (MHz)	Tol $\pm$ (%)	SRF min (MHz)	DCR max ( $\Omega$ )	Rated DC Current (A)	
						$I_{\text{sat}}$	$I_{\Delta T = 40^\circ\text{C}}$
PISP-6R8M-04	6.8	0.1	20	19	0.018	6.72	3.60
PISP-100M-04	10	0.1	20	17	0.026	5.21	3.60
PISP-150M-04	15	0.1	20	13	0.035	4.13	3.12
PISP-220M-04	22	0.1	20	10	0.050	3.54	2.80
PISP-330M-04	33	0.1	20	8	0.073	2.86	2.32
PISP-470M-04	47	0.1	20	6.1	0.112	2.34	1.60
PISP-680M-04	68	0.1	20	5.8	0.143	2.00	1.44
PISP-101M-04	100	0.1	20	4.1	0.230	1.64	1.28
PISP-151M-04	150	0.1	20	3.5	0.295	1.36	1.16
PISP-221M-04	220	0.1	20	3.1	0.463	1.12	0.94
PISP-331M-04	330	0.1	20	2.4	0.672	0.91	0.79
PISP-471M-04	470	0.1	20	2.0	0.996	0.80	0.64
PISP-681M-04	680	0.1	20	1.5	1.476	0.67	0.50
PISP-102M-04	1000	0.1	20	1.3	1.980	0.57	0.42
PISP-222M-04	2200	0.1	20	1.0	4.488	0.34	0.30
PISP-103M-04	10000	0.1	20	0.8	21.480	0.17	0.12

**Core Material** : Ferrite  
**Base Material** : Plastic

Revision date : 25 Jul 2018

**SPQ** : Taped / Reel 250 [-04]

**Remarks :**

$I_{\text{sat}}$  &  $I_{\Delta T}$  - see description in Inductors Technical Data.  
Terminal clip with lead-free tinned surface for SMT-Reflow soldering.